



NTC thermistors for inrush current limiting

Leaded and coated disks,
insulation voltage 1000 VDC

Series/Type: B57236
Date: March 2006

Applications

- Switch-mode power supplies

Features

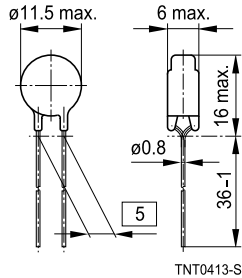
- Improved insulation voltage
- Useable in series connections up to 265 V_{rms}
- Coated thermistor disk
- Kinked leads of tinned copper wire
- Wide resistance range
- UL approval (E69802)

Options

Alternative lead configurations available on request

Delivery mode

Bulk (standard),
cardboard tape, reeled or in Ammo pack

Dimensional drawing


Dimensions in mm

Approx. weight 1.7 g

General technical data

Climatic category	(IEC 60068-1)		55/170/21	
Max. power	(at 25 °C)	P _{max}	2.4	W
Resistance tolerance		ΔR _R /R _R	±15	%
Rated temperature		T _R	25	°C
B value tolerance		ΔB/B	±3	%
Dissipation factor	(in air)	δ _{th}	approx. 14	mW/K
Thermal cooling time constant	(in air)	τ _c	approx. 50	s
Heat capacity		C _{th}	approx. 700	mJ/K
Test voltage	(t = 1 s)	V _{test}	1000	VDC

Electrical specification and ordering codes

R ₂₅ Ω	I _{max} (0...65 °C) A	No. of R/T char- acteristic	B _{25/100} K	C _{test} ¹⁾ 230 V μF	C _{test} ¹⁾ 110 V μF	Param. for R(I) ¹⁾ k	Param. for R(I) ¹⁾ n	Ordering code
2.5	5.5	1201	2700	200	800	0.621	-1.27	B57236S0259L002
3	5.0	1201	2700	300	1200	0.80	-1.31	B57236S0309L002
5	4.5	1202	2800	300	1200	0.761	-1.30	B57236S0509L002
8	3.7	1203	2900	300	1200	1.11	-1.34	B57236S0809L002
10	3.5	1203	2900	300	1200	0.942	-1.32	B57236S0100L002
12	3.2	1203	2900	300	1200	1.00	-1.32	B57236S0120L002
16	2.9	1207	2965	300	1200	1.08	-1.33	B57236S0160L002
20	2.8	1208	3065	300	1200	1.13	-1.34	B57236S0200L002
25	2.5	1208	3065	300	1200	1.22	-1.34	B57236S0250L002

1) For details on the capacitance C_{test} as well as on the parameters k and n refer to "Application Notes", chapters 2.6 and 2.7.

R_{25} Ω	I_{\max} (0...65 °C) A	No. of R/T char- acteristic	$B_{25/100}$ K	$C_{\text{test}}^{(1)}$ 230 V μF	$C_{\text{test}}^{(1)}$ 110 V μF	Param. for $R(I)^{(1)}$ k	Param. for $R(I)^{(1)n}$	Ordering code
50	1.9	1209	3165	300	1200	1.44	-1.38	B57236S0500L002
80	1.6	1304	3300	400	1600	1.64	-1.37	B57236S0800L002

Reliability data

Test	Standard	Test conditions	$\Delta R_{25}/R_{25}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature T: 170 °C t: 1000 h	< 10%	No visible damage
Storage in damp heat, steady state	IEC 60068-2-78	Temperature of air: 40 °C Relative humidity of air: 93% Duration: 21 days	< 5%	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: -55 °C Upper test temperature: 170 °C Number of cycles: 10	< 10%	No visible damage
Endurance		$I = I_{\max}$ t: 1000 h	< 10%	No visible damage
Cyclic endurance		$I = I_{\max}$, 1000 cycles On-time = 1 min Cooling time = 6 min	< 10%	No visible damage
Transient load		Capacitance = C_{test} Number of cycles: 1000	< 5%	No visible damage

Cautions and warnings for ICLs

The self-heating of a thermistor during operation depends on the load applied and the applicable dissipation factor.

When loaded with maximum allowable current/power and the specified dissipation factor is taken as a basis, the NTC thermistor may reach a mean temperature of up to 250 °C.

The heat developed during operation will also be dissipated through the lead wires. So the contact areas, too, may become quite hot at maximum load.

When mounting NTC thermistors you have to ensure that there is an adequate distance between the thermistor and all parts which are sensitive to heat or combustible.

1) For details on the capacitance C_{test} as well as on the parameters k and n refer to "Application Notes", chapters 2.6 and 2.7.

Cautions and warnings

General

See "Important notes" at the end of this document.

Storage

- Store thermistors only in original packaging. Do not open the package before storage.
- Storage conditions in original packaging: storage temperature $-25\text{ }^{\circ}\text{C} \dots +45\text{ }^{\circ}\text{C}$, relative humidity $\leq 75\%$ annual mean, maximum 95%, dew precipitation is inadmissible.
- Do not store SMDs where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or SMDs may stick together, causing problems during mounting.
- Avoid contamination of thermistors surface during storage, handling and processing.
- Avoid storage of thermistor in harmful environments like corrosive gases (SO_x, Cl etc).
- After opening the factory seals, such as polyvinyl-sealed packages, use the SMDs as soon as possible.
- Solder thermistors after shipment from EPCOS within the time specified:
SMDs: 12 months
Leaded components: 24 months

Handling

- NTC thermistors must not be dropped. Chip-offs must not be caused during handling of NTCs.
- Components must not be touched with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

Mounting

- When NTC thermistors are encapsulated with sealing material or overmolded with plastic material, the precautions given in chapter "Mounting instructions", "Sealing, potting and overmolding" must be observed.
- Electrode must not be scratched before/during/after the mounting process.
- Contacts and housings used for assembly with thermistor have to be clean before mounting.
- During operation, the thermistor's surface temperature can be very high (ICL). Ensure that adjacent components are placed at a sufficient distance from the thermistor to allow for proper cooling of the thermistors.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand this temperature.
- Make sure that thermistors (ICLs) are adequately ventilated to avoid overheating.
- Avoid contamination of thermistor surface during processing.